

ISM 915 MHz Ceramic Chip Antenna
Model: AA702
TELA chip antenna
Product Number: H2U64U1H2C0200

REFERENCE SPECIFICATION

Table of Contents

1	Introduction	3
2	Electrical Characteristics.....	4
2.1	Table with electrical properties:	4
2.2	Return Loss (S_{11})	5
2.3	VSWR (S_{11})	5
2.4	Frequency vs V.S.W.R. and Total Radiation Gain	6
2.5	Radiation Pattern (with 80x40mm ² Evaluation Board)	7
3	Layout	8
3.1	Antenna Dimensions	8
3.2	Evaluation Board with Antenna	9
3.3	Solder Land Pattern	10
4	Frequency tuning	11
4.1	Reference for frequency tuning element.....	12
5	Packing.....	13
6	Notes.....	14
6.1	Typical Soldering Profile for Lead-free Process	14
6.2	Operating and storage conditions:	15
6.3	Installation guide:	15
6.4	Reminders for users of Unictron’s 702 ceramic chip antennas	15

1 Introduction

Unictron's AA702 ceramic chip antenna is designed for ISM 915MHz band applications, covering frequencies 902 – 928 MHz. Fabricated with proprietary design and processes, AA702 shows excellent performance and is fully compatible with SMT processes which can decrease the assembly cost and improve device's quality and consistency.

Features

- * Stable and reliable in performances
- * Low profile, compact size
- * RoHS compliance
- * SMT processes compatible

Applications

- * ISM 915 MHz Band applications
- * IoT applications
- * LoRa / Sigfox
- * IEEE 802.11ah/ Wi-Fi Certified HaLow technology

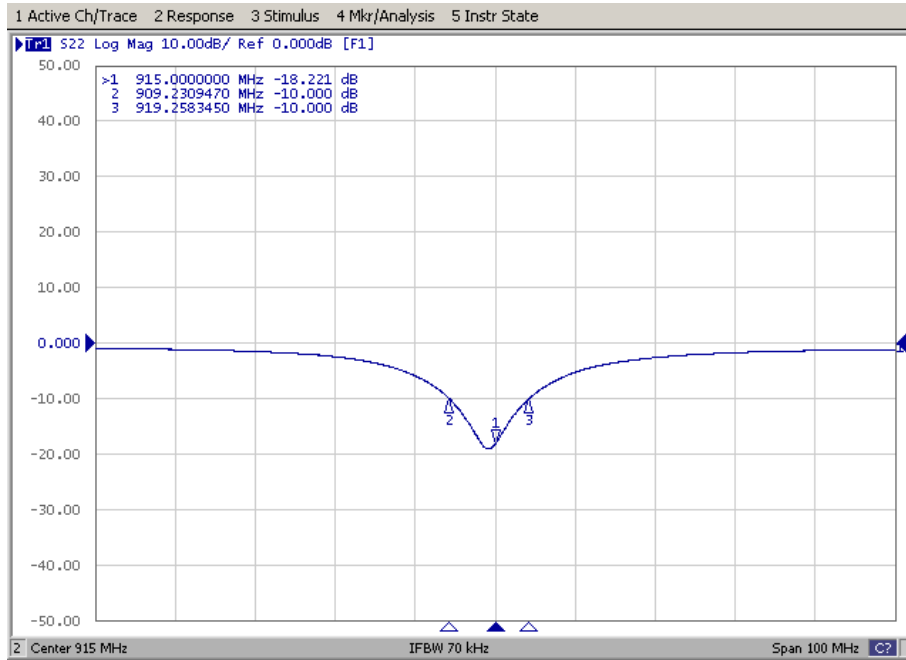
2 Electrical Characteristics

2.1 Table with electrical properties:

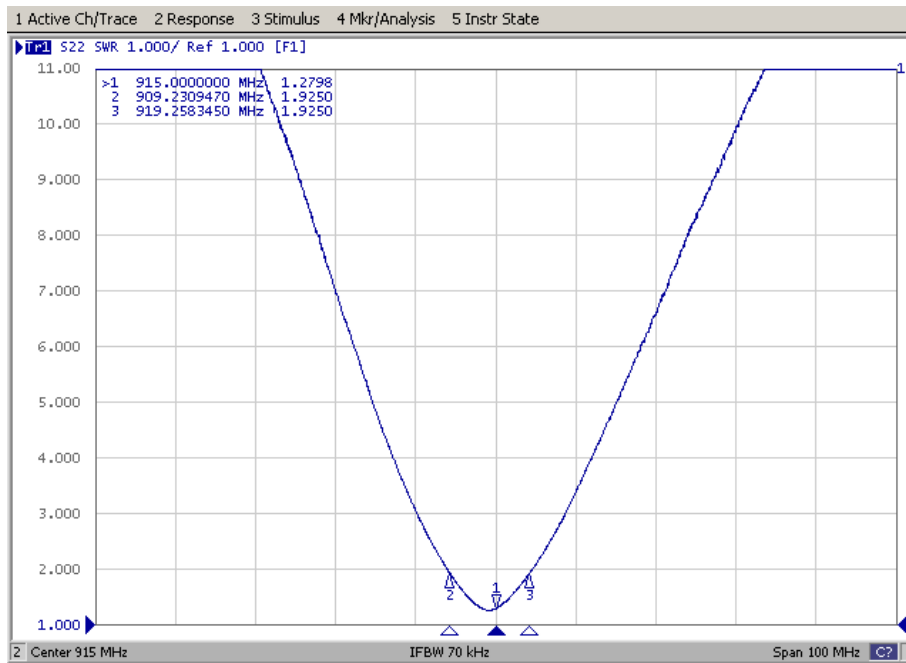
Characteristics		Specifications	Unit
Outline Dimensions		5.0 x 3.0 x 0.5	mm
Ground Plane Dimensions		80 x 40	mm
Working Frequency		902 – 928	MHz
VSWR (@ center frequency)*		2 Max.	
Characteristic Impedance		50	Ω
Polarization		Linear Polarization	
Peak Gain	(@ 915 MHz)	0.3 (typical)	dBi
Efficiency		52 (typical)	%

*Center frequency means the frequency with the lowest value in return loss of the chip antenna on the evaluation board.

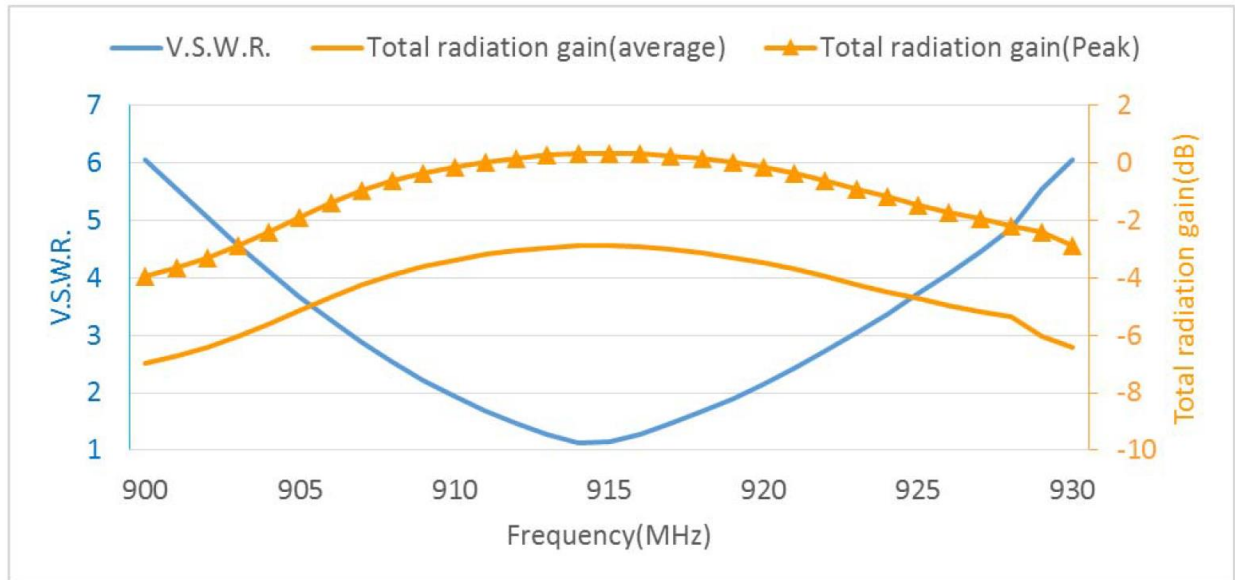
2.2 Return Loss (S_{11})



2.3 VSWR (S_{11})

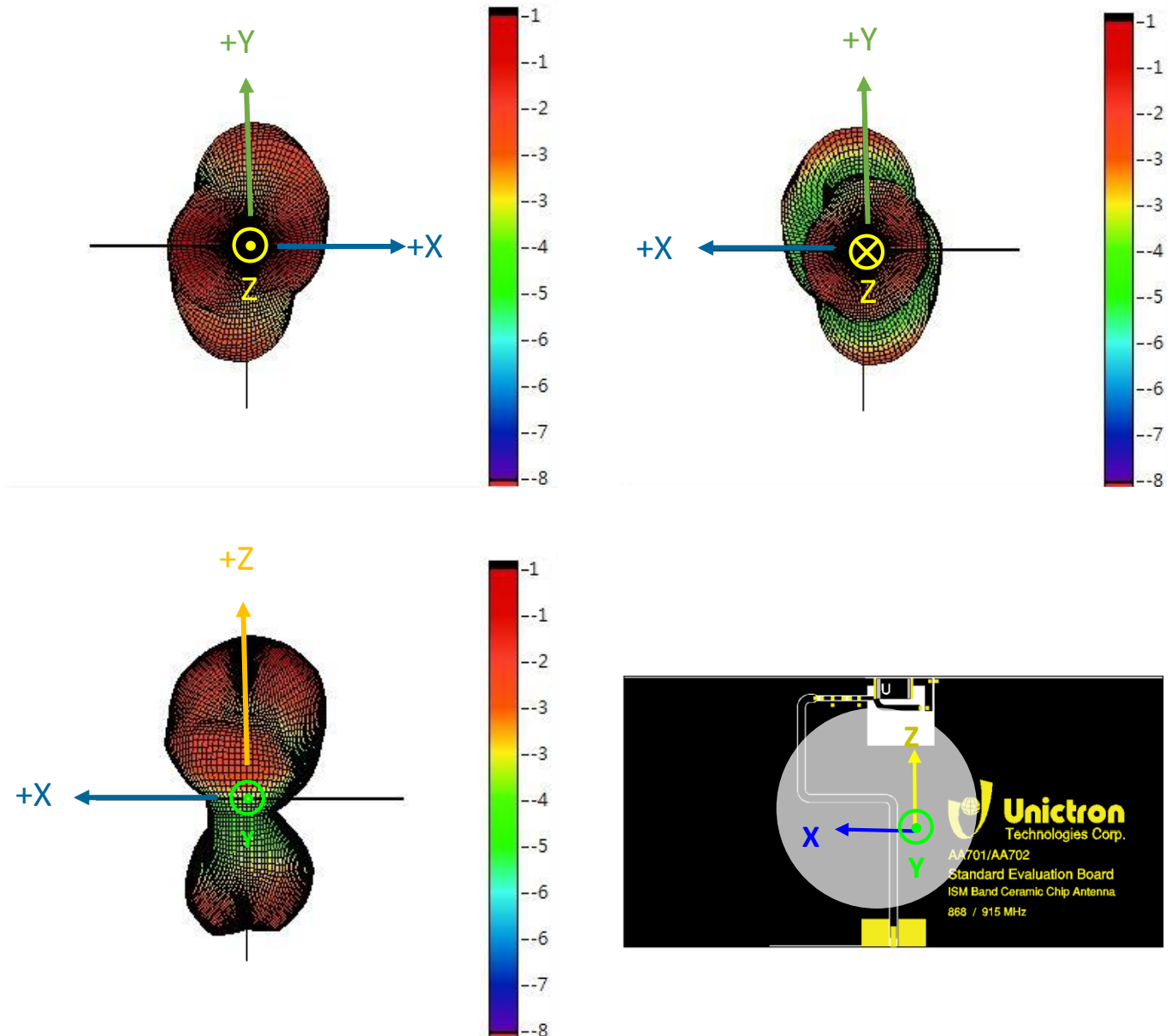


2.4 Frequency vs V.S.W.R. and Total Radiation Gain



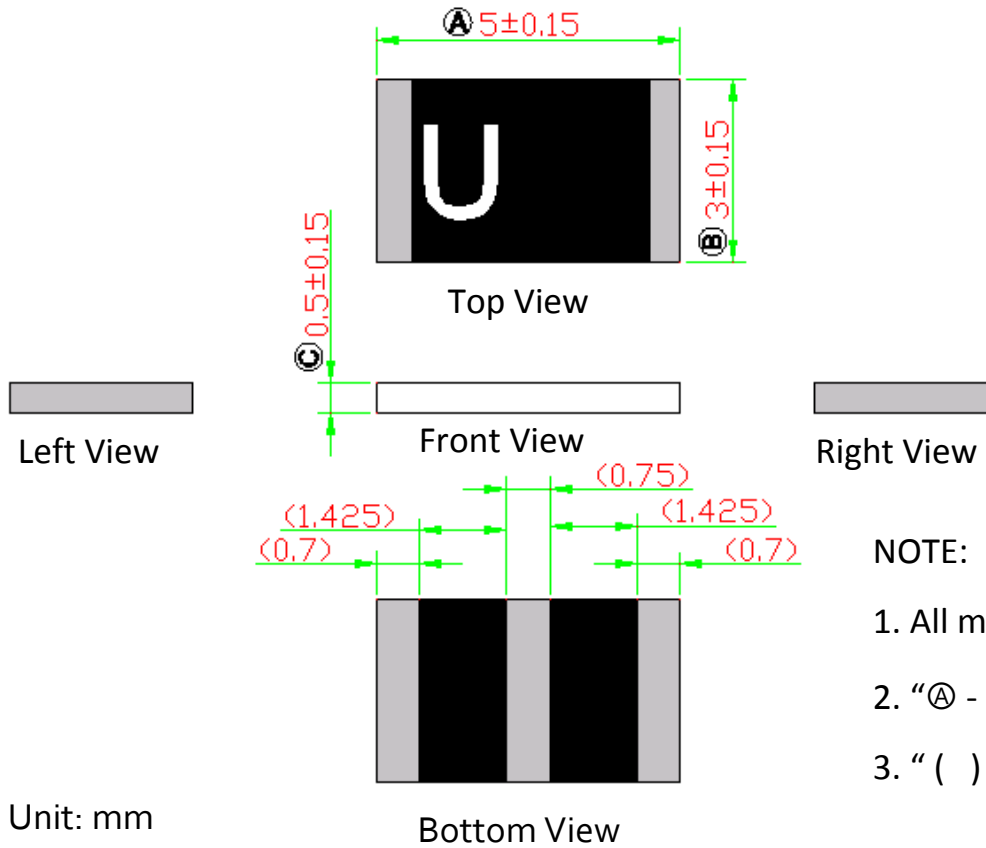
2.5 Radiation Pattern (with 80x40mm² Evaluation Board)

3D Gain Pattern @ 915 MHz (unit: dBi)



3 Layout

3.1 Antenna Dimensions



NOTE:

1. All materials are RoHS compliant
2. "A - C" Critical dimensions
3. "()" Reference dimensions

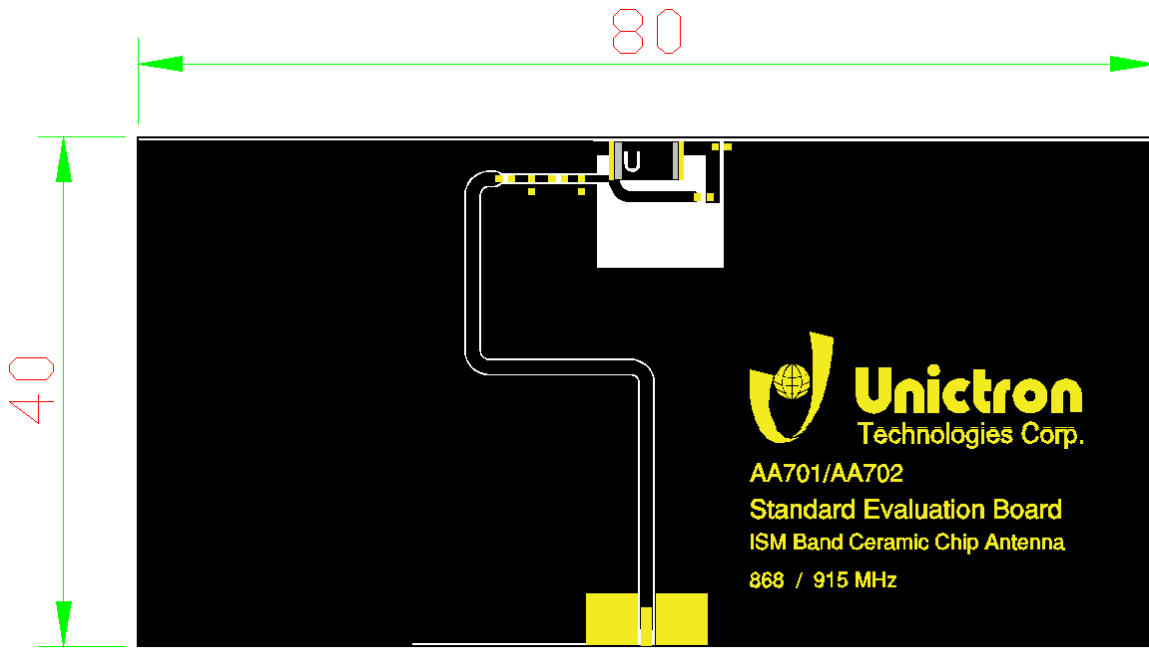
Unit: mm

PIN Definitions



PIN	1	2	3
Soldering Pad	Signal	Tuning/Ground	N/C

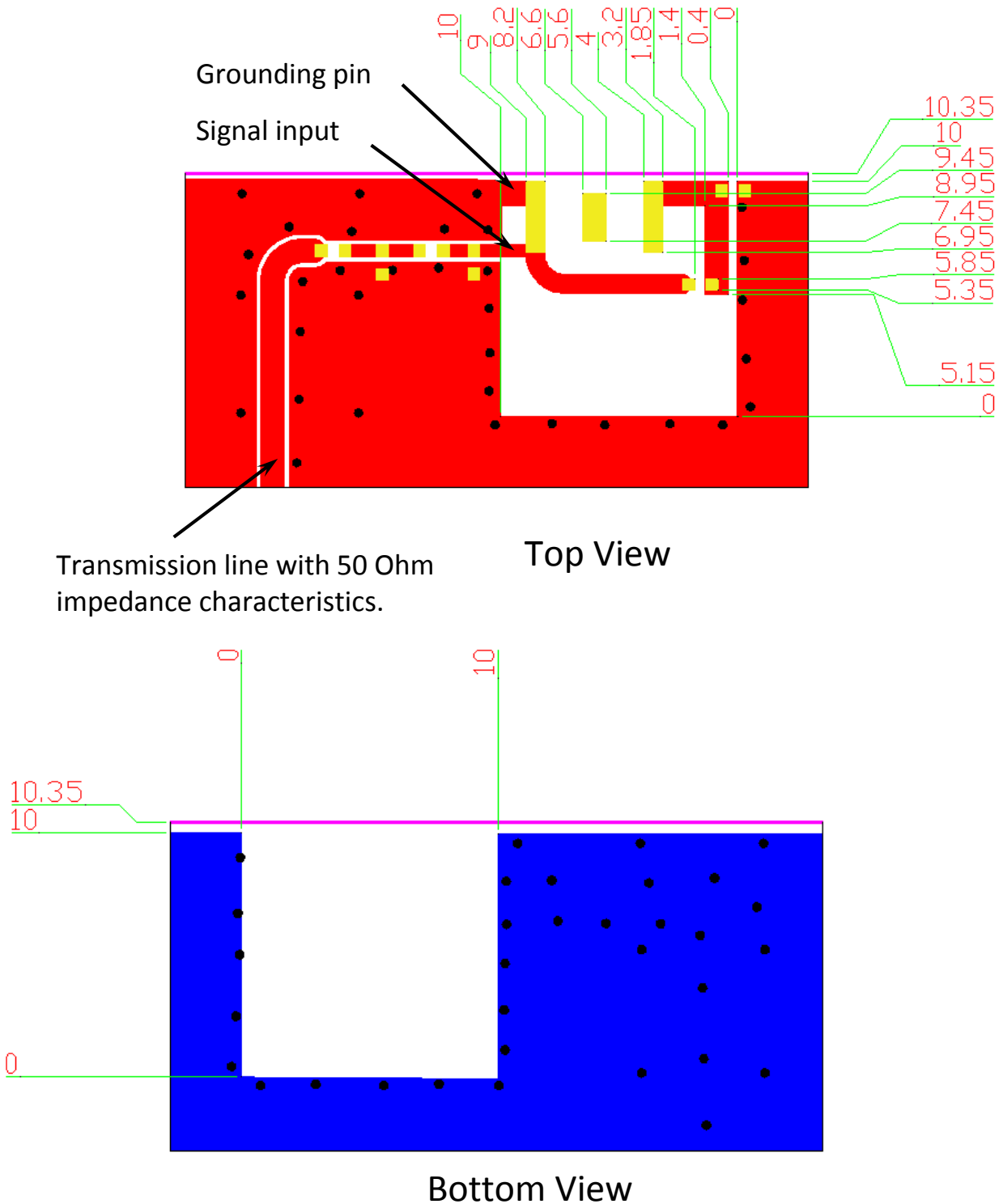
3.2 Evaluation Board with Antenna



Unit: mm

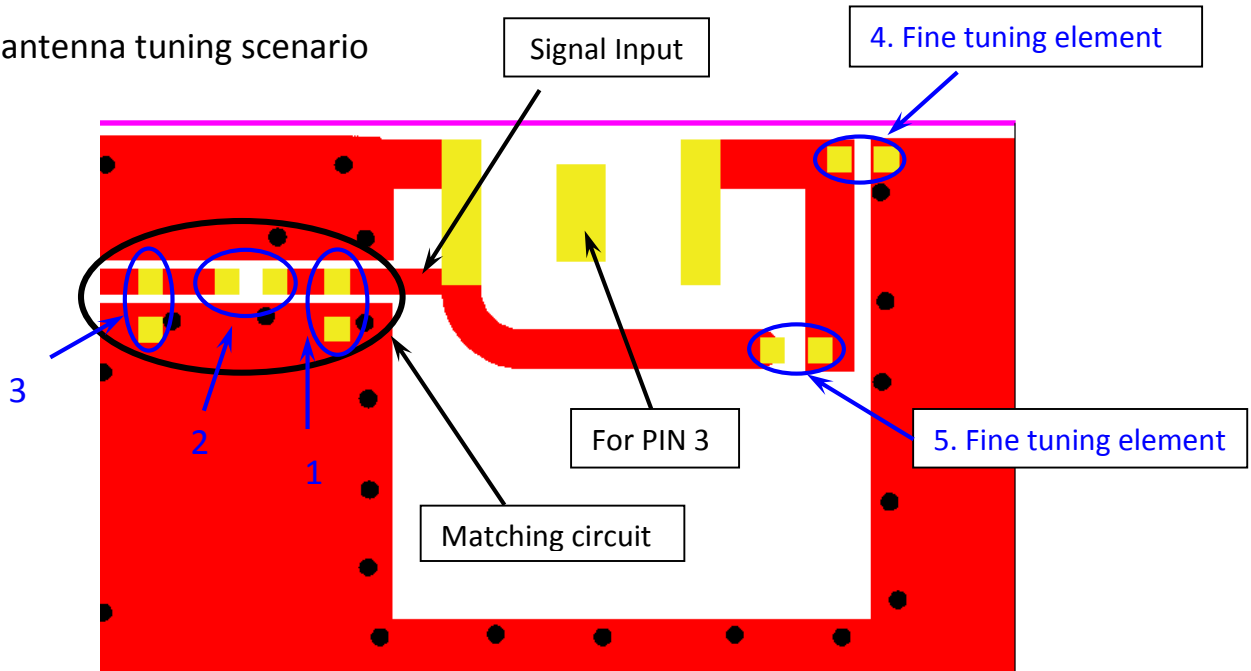
3.3 Solder Land Pattern

The solder land pattern (gold marking areas) is shown below. Recommendation on matching circuit will be provided according to customer's installation conditions.

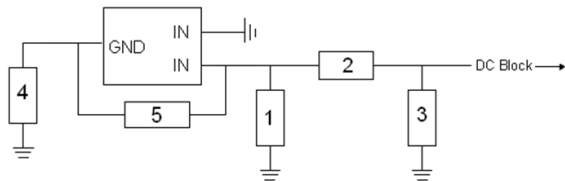


4 Frequency tuning

Chip antenna tuning scenario



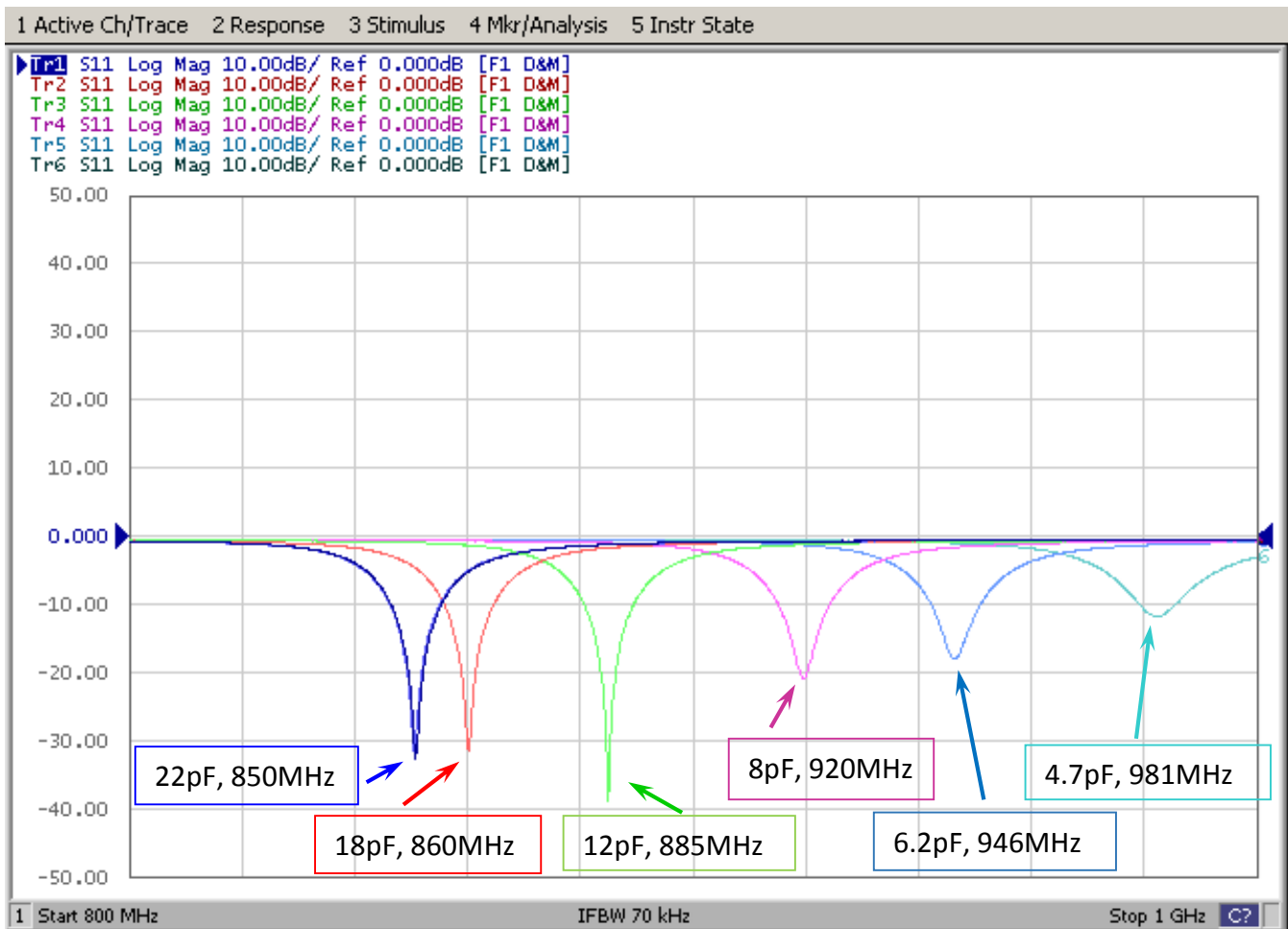
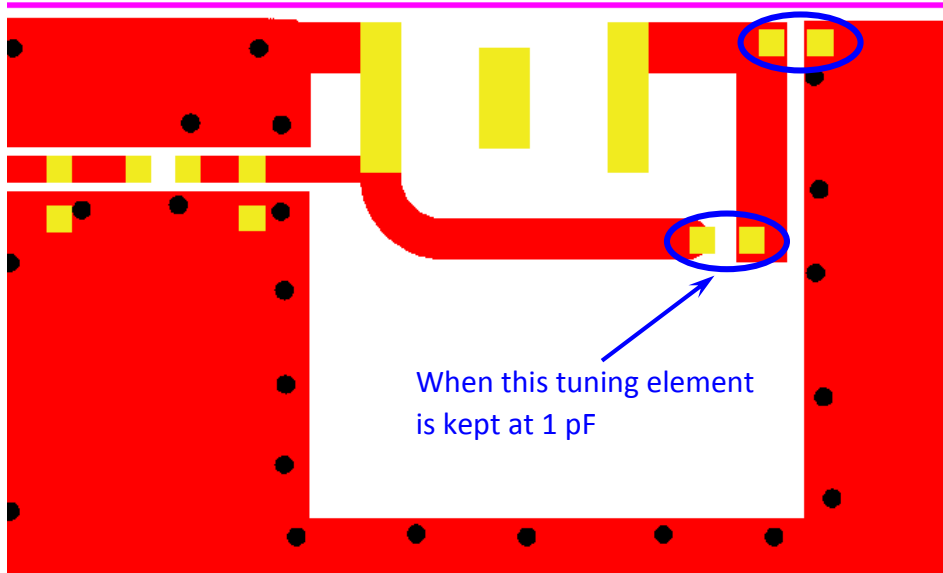
With the following recommended values of matching and tuning components, the center frequencies will be about 915 MHz at out standard 80x40 mm² evaluation board.



System Matching Circuit Component			
Location	Description	Vendor	Tolerance
1	N/A	-	-
2	1.2 nH (0402)	DARFON	±0.1 nH
3	0.2 pF (0402)	DARFON	±0.1 pF
4	18 pF (0402)	DARFON	±2%
Fine tuning element			
5	0.5 pF (0402)	DARFON	± 0.1 pF
Fine tuning element			

If you are using a PCB board of different dimensions, the values of suitable matching and tuning components may differ. Feel free to contact a Unictron’s representative at e-sales@unictron.com for further assistance adjusting these components, optimizing PCB layout and antenna’s performance.

4.1 Reference for frequency tuning element

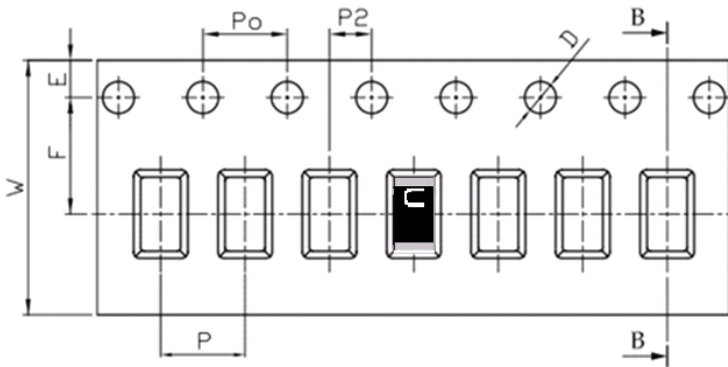


5 Packing

1. Quantity/Reel: 6000 pcs/Reel
2. Plastic tape:

a) Tape drawing:

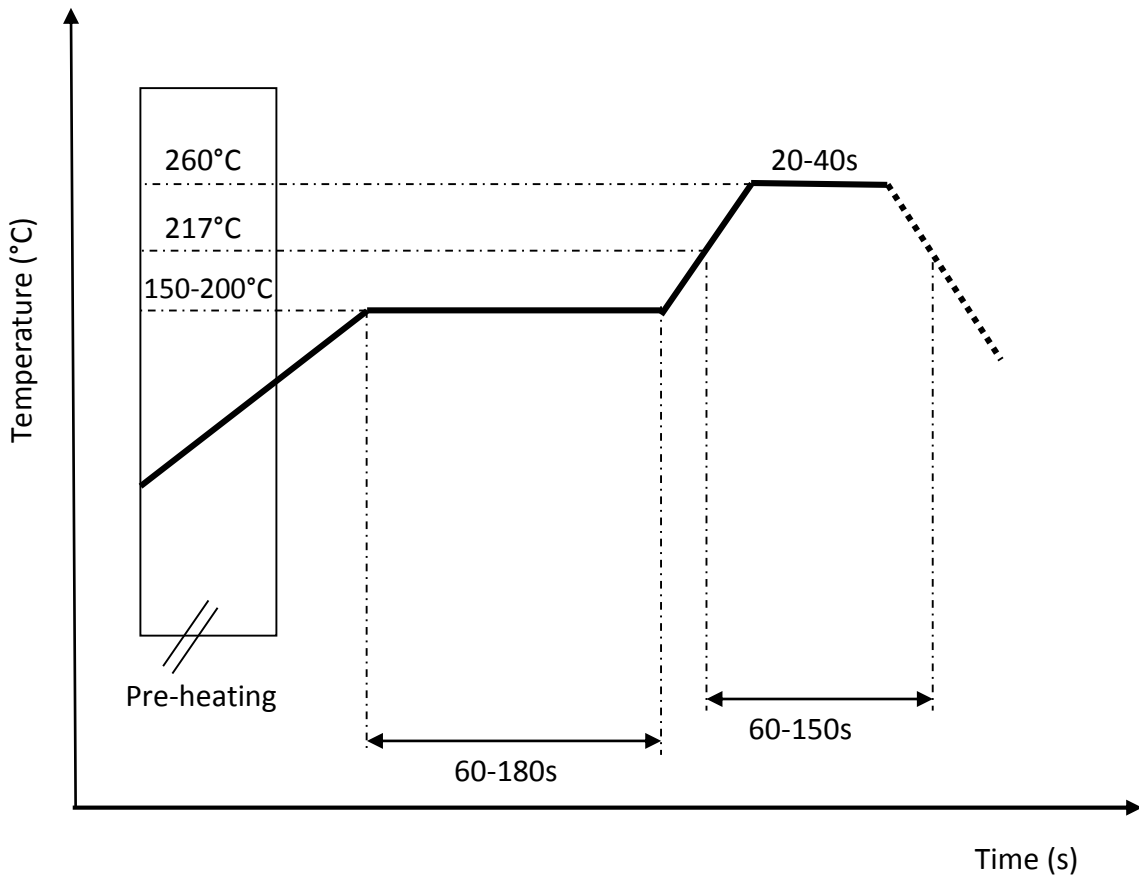
b) Tape dimensions (unit: mm)



Feature	Specifications	Tolerances
W	12.00	±0.30
P	8.00	±0.10
E	1.75	±0.10
F	5.50	±0.10
P2	2.00	±0.10
D	1.20	+0.10 -0.00
P0	4.00	±0.10
10P0	40.00	±0.20

6 Notes

6.1 Typical Soldering Profile for Lead-free Process



6.2 Operating and storage conditions:

Operating:

Maximum Input Power: 2W

Operating Temperature: -40°C to +85°C

Storage:

Storage Temperature -5°C to +40°C

Relative Humidity: 20% to 70%

Shelf Life: 1 year

6.3 Installation guide:

Request Unictron's application notes "General guidelines for the installation of Unictron's chip antennas" for further information at e-sales@unictron.com.

6.4 Reminders for users of Unictron's AA702 ceramic chip antennas

- 6.4.1. This chip antenna is made of ceramic materials which are relatively more rigid and brittle compared to printed circuit board materials. Bending of circuit board at the locations where chip antenna is mounted may cause the cracking of solder joints or antenna itself.
- 6.4.2. Punching/cutting of the break-off tab of PCB panel may cause severe bending of the circuit board which may result in cracking of solder joints or chip antenna itself. Therefore break-off tab shall be located away from the installation site of chip antenna.
- 6.4.3. Be cautious when ultrasonic welding process needs to be used near the locations where chip antennas are installed. Strong ultrasonic vibration may cause the cracking of chip antenna solder joints.

Presented data were measured on reference PCB (ground) as shown in this specification. When the antenna placement or size of the PCB is changed, antenna performance and values of matching components may differ from data shown here.

Information presented in this Reference Specification is believed to be correct as of the date of publishing. Unictron Technologies Corporation reserves the rights to change the Reference Specification without notice due to technical improvements, etc. Please consult with Unictron's engineering team about the latest information before using this product. Per request, we may provide advice and assistance in implementing this antenna to a customer's device by simulation or real measurement of the interested device in our testing facilities.

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